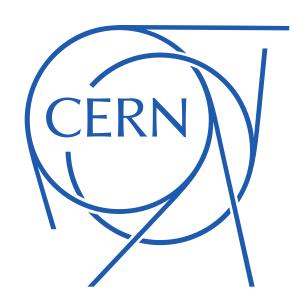
Chemical & Electropolishing facility for niobium (HL-LHC) and copper (FCC) substrates



TTC 2020 CERN 4-7 February 2020



Workshop at B. 118



Motivations

BCP of RFD & DQW complex geometries

Electropolishing of 400MHz cavities

Advantages of horizontal polishing

- Flushing of produced gas
- Less defects (bubbles)
- Increased homogeneity

Drawback → complexity and cost (316L SS, PVDF, FKM, ...)

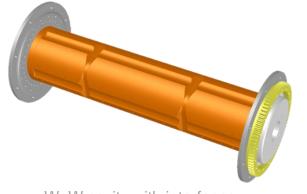
Advantages of vertical polishing

- Transposable to an industrialised process



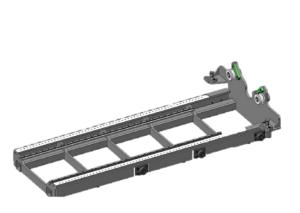


Machine overview

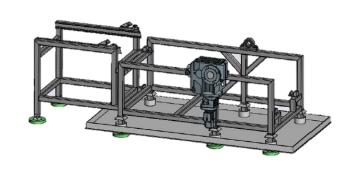


| Size limitations | | | | |
|------------------|----------|----------------|--|--|
| Length | Diameter | Weight (empty) | | |
| 1.5 m | 1 m | 300 kg | | |

WoW cavity with interfaces





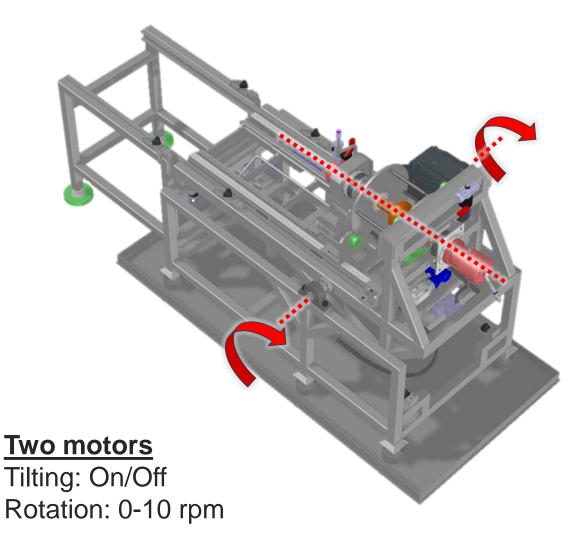


Cart Tilting frame Fixed frame



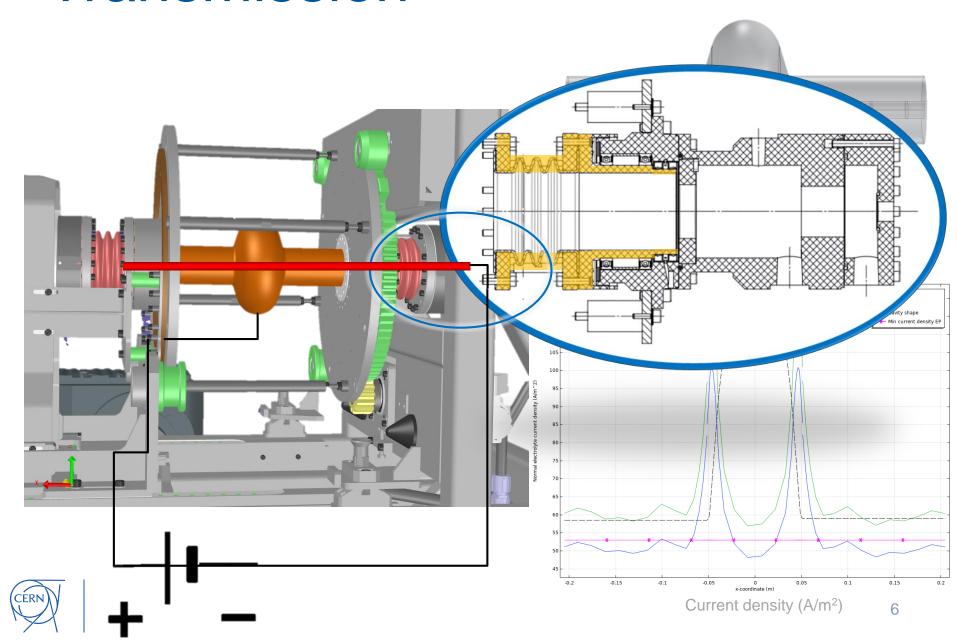
Motion







Transmission



Chemical assemblies

Niobium

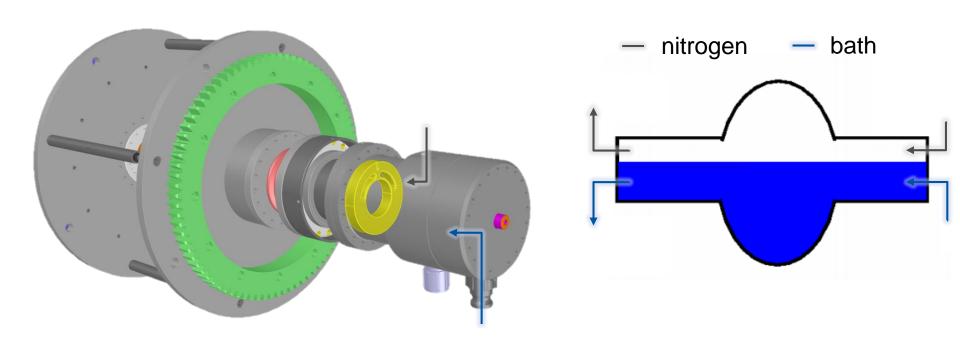
Copper







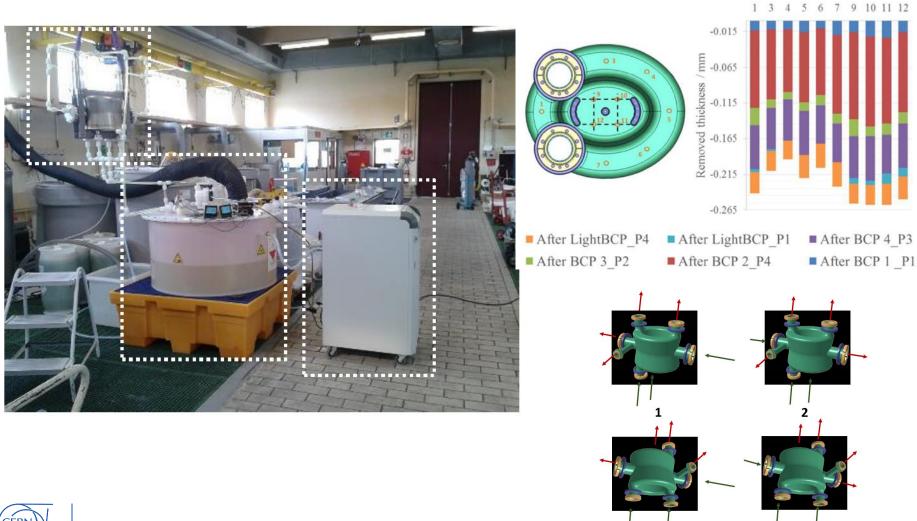
Nitrogen venting



- Inert atmosphere: average H₂ concentration 0.1% (LFL 4%)
- Reduced contact time of hydrogen with substrate

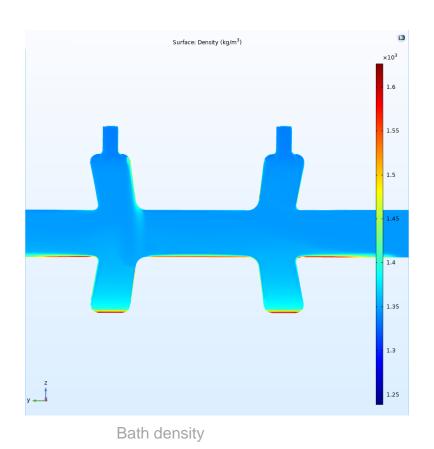


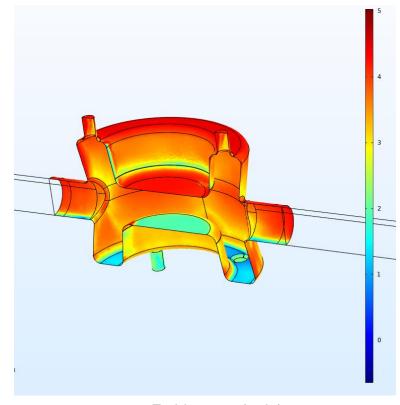
Previous setup



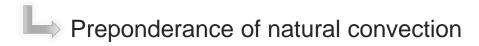


Previous setup - simulation



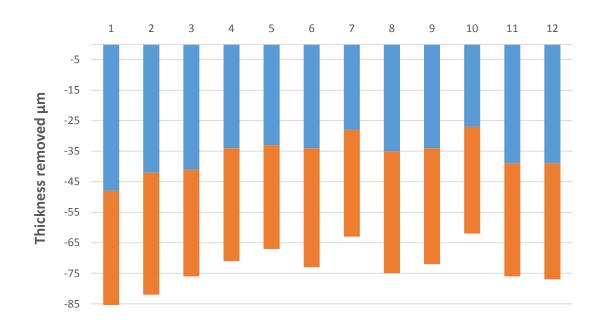


Etching rate (ratio)

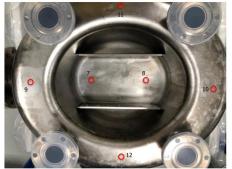




PoP DQW results







| After BCP1 | | After BCP2 | |
|------------|-----|------------|-----|
| Average | -36 | Average | -37 |
| Max | -48 | Max | -40 |
| Min | -27 | Min | -34 |

Ti 10.5°C 50 min

T 14.2°C 60 Min

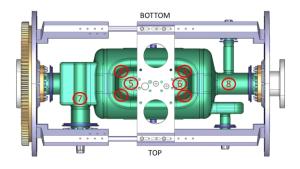
Average thickess removed from weight: 58 µm

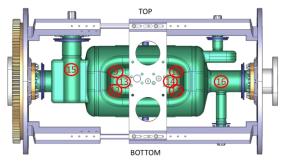
Precision: ± 5 μm

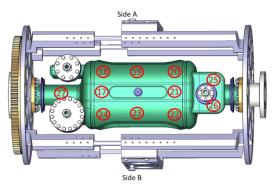
The probe changed after the reference measurement

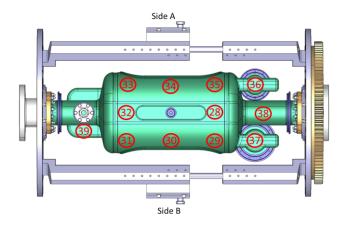


RFD results









Average thickness removed : 87 μm

Next steps

- BCP on RFD cavities (3 bulk, 2 light)
- Consolidation of our model
- EP on 1,3GHz single cell copper cavity
- EP on 400 MHz



